



Sigfox Module WSG303S

Compact-sized
With Ultra-low Power
Consumption

RF on pad







Sigfox Support



Zone: RC 1/3/5/6/7



AT Commands



Extended Temperature Range: -40°C to +85°C



Ultra-Low Power Consumption (2.2uA @ sleep mode)

WSG303S(RC1/3/5/6/7) is a Sigfox modem module for the low power wide area network (LPWAN) market. It is designed with STM's system S2-LP+STM32 MCU for the European, Japan, South Korea and India market.

The module was designed for high performance, high quality, low cost, small form factor and most importantly, high RF power of up to 14dBm. The design is fully compliant to ETSI regulations. The Sigfox application is running on SMT32 MCU at high efficiency executed at high efficiency using its internal 32bit core Cortex-M0 processor.

Every module is preloaded with Sigfox application software, module specific ID/KEY/PAC as referring to Sigfox network system. The preloaded software also includes a bootloader which allows software update or future user application development.



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SIGFOX VERIFIED CERTIFICATE



Sigfox Verified™ Certificate M_004E_728B_01

Congratulations LiteOn, the following product is now Sigfox Verified™ certified:



PRODUCT COMMERCIAL NAME: ... WSG303S Sigfox module PRODUCT MODEL NAME: WSG303S RADIO CONFIGURATION: RC1; RC3; RC5; RC6; RC7 TEST REPORT: CORP-13438; 60412161-001 LAYOUT VERSION: V03 SCHEMATIC VERSION: V03 BOM VERSION: V03 FIRMWARE VERSION: V2.0.1.5 V2.8.4 FDL + addon V0.6.0 SIGFOX LIB: 4096 MESSAGE ROLLOVER COUNTER: .. BUIL-945 SIGFOX REFERENCE: CERTIFICATION DATE: 03/09/2020 SIGFOX FEATURES: DOWNLINK. PAYLOAD ENCRYPTED..... MONARCH.....

This certificate is valid for this product only. Any change to the certified product must be reported to Sigfox as it may lead to a renewal of the RF & protocol Tests.

The Sigfox Verified™ logo must be used in respect of Sigfox branding guidelines.





General Feature

 General Sigfox module for Smart City, Smart Agriculture , Smart Industry, IOT Application

Compact Form Factor: 22.5 x 16.5 x 3.0 mm51 Pin LGA Pad for PCB SMT mounting

Interface: I2C*1/UART*1/GPIO*3/ADC*2/SWD*1

■ Temperature range: -40°C to +85°C

■ Supply voltage: 2.0 ~ 3.6V

Frequency range: ISM RC1/RC7(868MHz), RC3/RC5(923MHz), RC6(865MHz),

Preloaded Sigfox application with ID/KEY/PAC and bootloader for firmware update

Product Specifications

RF Function

Standard Sigfox Network System

Interface I2C/UART/GPIO/ADC/SWD

Transmit Output Power 14dBm

Data Rate Uplink: 100bps

Downlink: 600bps

Modulation Techniques

Uplink DBPSK Modulation

Downlink GFSK Modulation

Sigfox Frequency bands RC 1/3/5/6/7

Operating Voltage 2.0 ~ 3.6V

Operating Temperature -40 ~ 85 degree C

Tx mode(TX period): 21mA

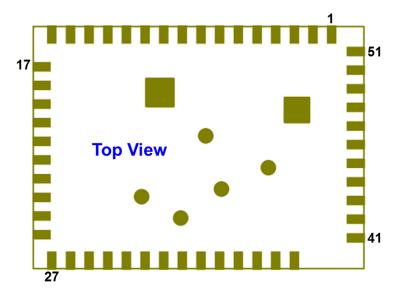
Uplink(TX 1 frame): 24mA

Current consumption Downlink:14mA

Normal mode: 5mA Sleep mode: 2.2 uA



◆ Module Pinout

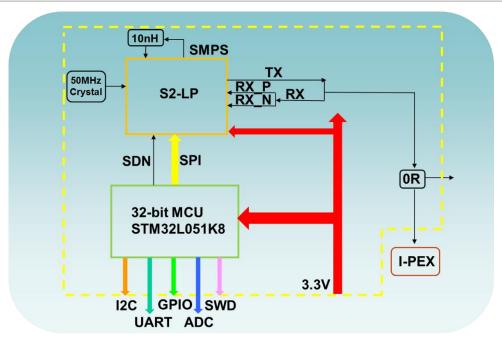


PIN DEFINITION

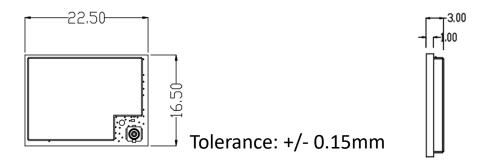
Pin.	Description	Function	Pin	Description	Function
1,2,3,4,5,15,16,39, 40,41,42,43,44,45, 47,48,49,50,51	GND	GND		PA11	PA11
6	SDO	PA6(Suggest to floating)	25	PA12	PA12
7	SDI	PA7(Suggest to floating)	26	SWDIO	PA13 (MCU debugging and programming)
8	SCLK	PB3(Suggest to floating)	27	SWCLK	PA14 (MCU debugging and programming)
9	CSN	PA1(Suggest to floating)	28	NC	NC
10	GPIO	PA0	29	PB4	PB4
11	PA4	PA4	30	PB5	PB5
12	PB1	PB1	31	PB6	PB6
13	PA15	PA15	32	PB7	PB7
14	SDN	S2LP shut down pin, MCU control, please floating	33	NRST	NRST (MCU Reset)
17	USART2_TX	PA2 (115200bps) Default UART	34	воото	BOOTO (Floating or Low)
18	USART2_RX	PA3 (115200bps) Default UART	35	PB8	PB8
19	PA5	PA5	36	ΧI	PC14-OSC_IN (Ready for External Crystal)
20	РВО	PB0	37	хо	PC15-OSC32_OUT (Ready for External Crystal)
21	PB2	PB2		VDD	VDD_3V3
22	PA9	PA9		ANT1	SigFox Antenna
23	PA10	PA10			



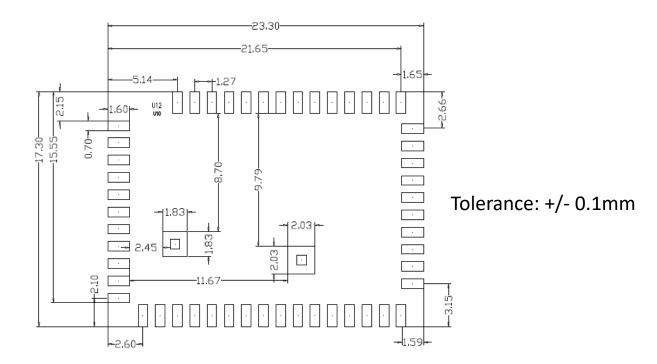
BLOCK DIAGRAM



♦ Module Dimension



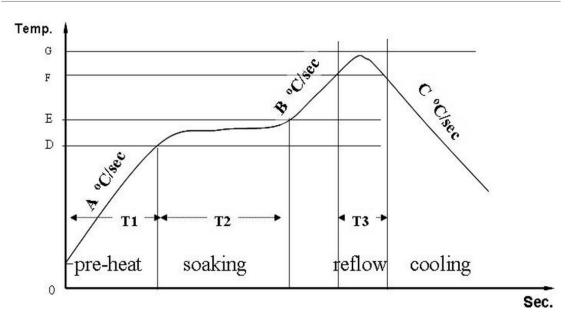
◆ RECOMMENDED FOOTPRINT





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RECOMMENDED REFLOW PROFILE

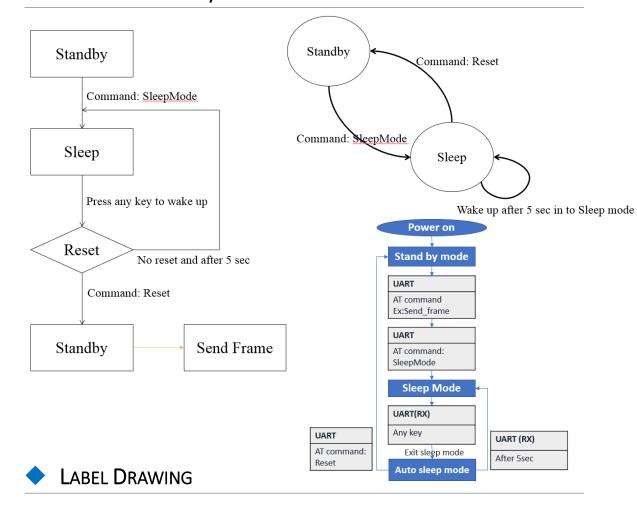


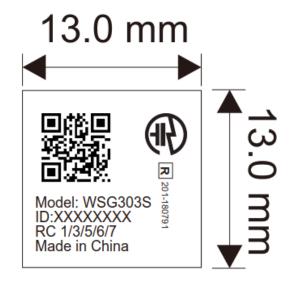
Standard conditions for reflow soldering:

- a. Pre-heating Ramp (A) (Initial temperature: 150°C): 1~2.5°C/sec;
- b. Soaking Time (T2) (150°C~180°C): 60sec~100sec;
- c. Peak Temperature (G): 230~250°C;
- d. Reflow Time (T3) (>220°C): 30~60 sec;
- e. Ramp-up Rate (B): 0~2.5°C/ sec;
- f. Ramp-down Rate (C): 1~3°C/ sec.



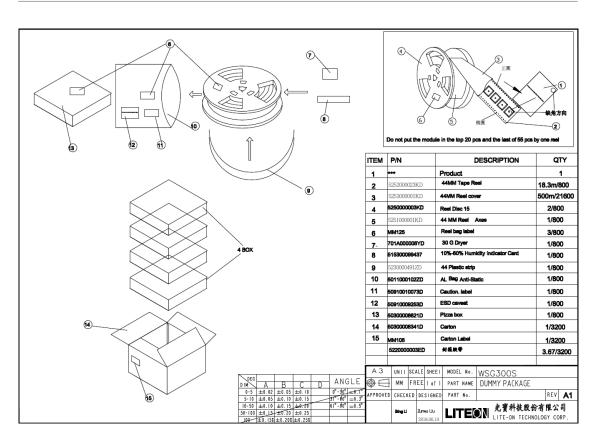
◆ FLOW OF STANDBY/SLEEP MODE

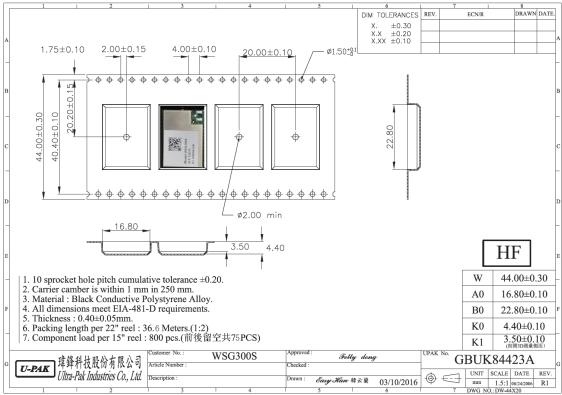






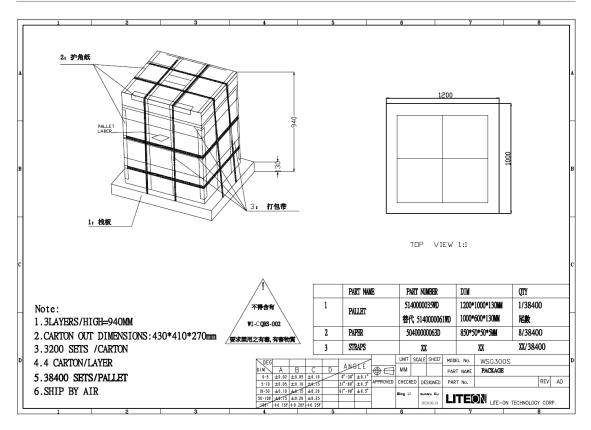
PACKAGING SPEC

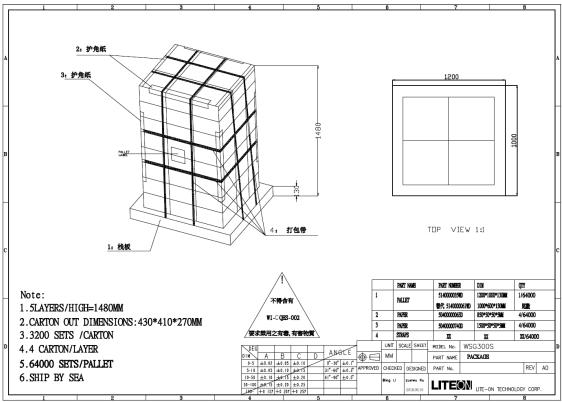






PACKAGING SPEC







CHANGE LIST

Rev	Date	Author	Change List	
V1.0	2018.02.12	Kaysa Lee	Preliminary	
V1.1	2018.06.11	Kelly Hsu	Update Voltage supply Update Current consumption Update AT Command List	
V1.2	2018.06.19	Kaysa Lee	Add Packaging spec	
V1.3	2018.07.02	Kelly Hsu	Add Reflow profile Add Label Drawing	
V1.4	2018.09.03	Kaysa Lee	Add sigfox P1 Cert	
V1.5	2018.09.25	Kaysa Lee	Update Power consumption data	
V1.6	2018.10.04	Kaysa Lee	Add Standby/Sleep Flow chart	
V1.7	2018.12.04	Kelly Hsu	Update Recommended footprint	
V1.8	2018.12.27	Kaysa Lee	Update sigfox P1 cert. to support RC 1/3/5 Update AT Command for RC3/5	
V1.9	2019.07.25	Kelly Hsu	Update sigfox P1 cert. to support RC 1/3/5/6 Modify AT Command List and Label Drawing	
V2.0	2020.04.06	Kelly Hsu	Modify Pin Definition	
V2.1	2020.09.14	Kelly Hsu	Update sigfox P1 cert. to support RC 1/3/5/6/7 Update AT Command for RC7 Modify Label Drawing	
V2.2	2021.01.27	Kelly Hsu	Update Recommended footprint	